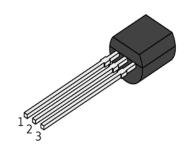


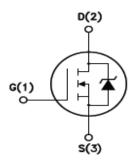


N-CHANNEL POWER MOSFET





- 1. Gate
- 2. Drain 3. Source



CDB1N45

TO-92 Plastic Package

Features

- 1) 100% Avalanche Tested
- 2) Typical $R_{DS(on)} = 4.1\Omega$
- 3) Extremely High dv/dt Capability
- 4) Gate Charge Minimized

Applications

- 1) Switch Mode Power Supplies (SMPS)
- 2) Low Power, Low Cost CFL (Compact Fluoroscent Lamps)
- 3) Low Power Battery Chargers

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	
Drain - Source Voltage (V _{GS} =0)	$V_{ m DS}$	450	V	
Drain - Gate Voltage (R _{GS} =20kΩ)	V_{DGR}	450	V	
Gate - Source Voltage	V_{GS}	±30	V	
Continuous Drain Current at T _C = 25°C	I _D	0.5	Α	
Continuous Drain Current at T _C = 100°C	I _D	0.315	Α	
Pulsed Drain Current	* I _{DM}	2	Α	
Total Power Dissipation at T _C = 25°C	P _{TOT}	3.1	W	
Derating Factor		0.025	W/°C	
Peak Diode Recovery Voltage Slope	dv/dt ⁽¹⁾	3	V/ns	
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C	

^{*} Pulse Width Limited by Safe Operating Area

Note 1. - $I_{SD} \le 0.5A$, $di/dt \le 100A/\mu s$, $V_{DD} \le V_{(BR)DSS}$, $Tj \le Tjmax$







ELECTRICAL CHARACTERISTICS (T_c = 25°C Unless otherwise Specified)

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
ON / OFF						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0$, $I_D = 250 \mu A$	450			V
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = Max Rating, V_{GS} = 0V			1	μΑ
		V_{DS} =Max Rating, V_{GS} =0V, T_{J} = 125°C			50	μΑ
Gate-Body Leakage Current	I _{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			±100	nA
Gate - Threshold Voltage	V _{GS (th)}	$V_{DS} = V_{GS_1} I_{D=250 \mu A}$	2.3	3	3.7	V
Static Drain - Source On -State Resistance	R _{DS(ON)}	$V_{GS} = 10V, I_D = 0.5A$		4.1	4.5	Ω
Dynamic Characteristics	. ,					
Forward Transconductance	gfs ⁽¹⁾	$V_{DS} > I_{D(ON)} X R_{DS(ON)MAX},$ $I_{D} = 0.5A$		1.1		S
Input Capacitance	Ciss	$V_{DS} = 25V$ $V_{GS} = 0$ $f = 1.0 \text{ MHz}$		160		pF
Output Capacitance	Coss			27.5		
Reverse Transfer Capacitance	Crss			4.7		
Switching Characteristics	1					
Total Gate Charge	Qg	V_{DS} = 360V, I_{D} = 1.5A, V_{GS} = 10V, R_{G} =4.7 Ω		7	10	
Gate - Source Charge	Qgs			1.3		nC
Gate - Drain Charge	Qgd	- 10V, NG-4.722		3.2		
Turn-on Delay Time	td(on)	V_{DD} =225V, I_{D} =0.5A, V_{GS} =10V, R_{G} =4.7 Ω , (Resistive Load, See Fig.3)		6.7		- ns
Rise Time	tr			4		
Off-Voltage Rise Time	$t_{r(Voff)}$	V_{DD} =360V, I_{D} =1.5A, V_{GS} =10V, R_{G} =4.7 Ω , (Inductive Load, See Fig.5)		8.5		ns
Fall Time	tf			12		
Cross-over Time	tc			18		
Source-Drain Diode Characteristics						
Source - Drain Current	I_{SD}				1.5	Α
Source - Drain Current (pulsed)	I _{SDM} (2)				6	Α
Forward On Voltage	V _{SD} ⁽¹⁾	$V_{GS} = 0$, $I_{SD} = 1.5A$			1.6	V
Reverse Recovery Time	t _{rr}	V _{DD} = 100V, I _{SD} = 1.5A,		225		ns
Reverse Recovery Charge	Q _{rr}	di/dt = 100A/μs, Τ _J =150°C,		530		nC
Reverse Recovery Current	I _{RRM}	(see test circuit, Fig.5)		4.7		Α

Notes:

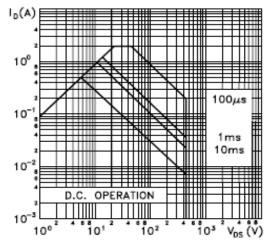
- 1) Pulse Duration = $300\mu s$, Duty Cycle = 1.5%
- 2) Pulse Width Limited by Safe Operating Area



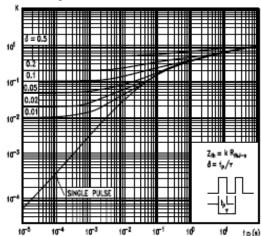


TYPICAL CHARACTERISTICS CURVES

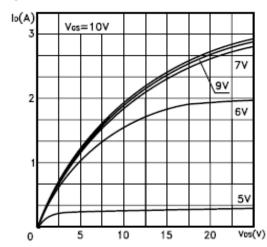
SafeOperatingArea



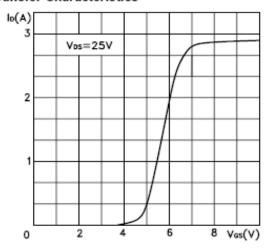
Thermallmpedance



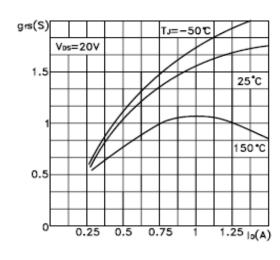
Output Characteristics



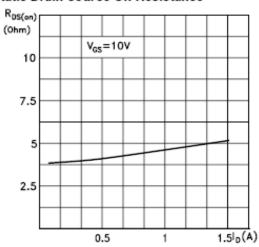
Transfer Characteristics



Transconductance



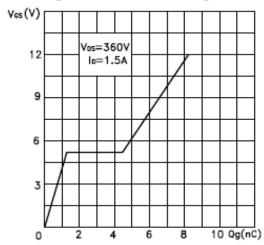
Static Drain-source On Resistance



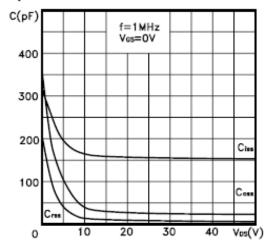




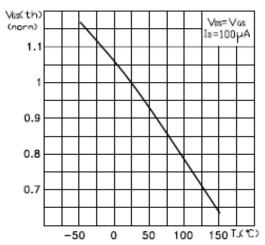
Gate Charge vs Gate-source Voltage



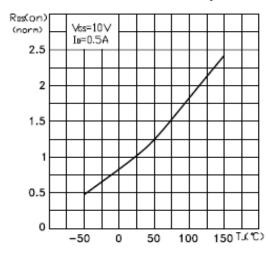
Capacitance Variations



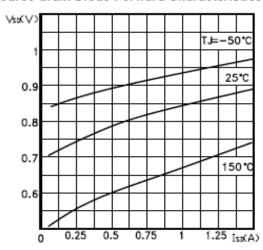
Normalized Gate Threshold Voltage vs Temp.



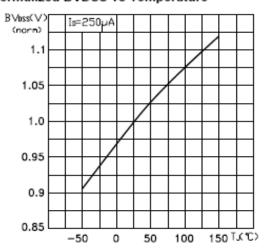
Normalized On Resistance vs Temperature



Source-drain Diode Forward Characteristics



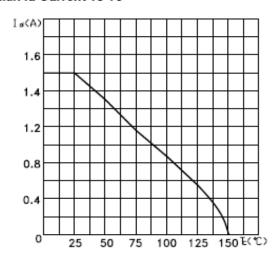
Normalized BVDSS vs Temperature



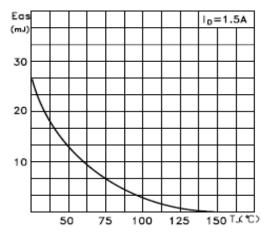




Max Id Current vs Tc



Maximum Avalanche Energy vs Temperature







TEST CIRCUITS AND WAVEFORMS

Fig. 1: Unclamped Inductive Load Test Circuit

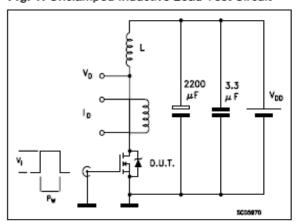


Fig. 3: Switching Times Test Circuit For

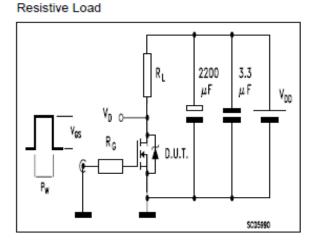


Fig. 5: Test Circuit ForInductive Load Switching And Diode Recovery Times

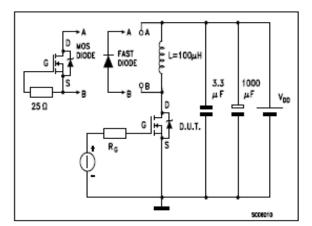


Fig. 2: Unclamped Inductive Waveform

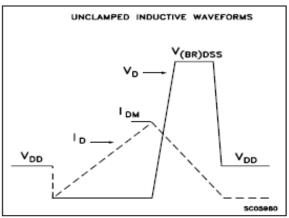
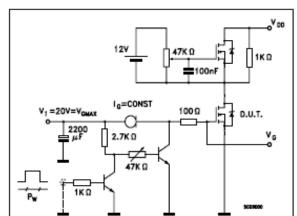


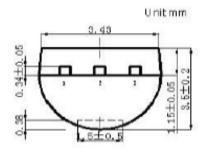
Fig. 4: Gate Charge test Circuit

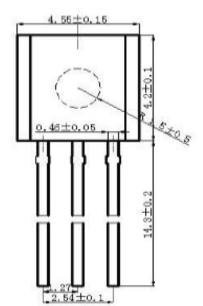






TO-92 PACKAGE OUTLINE AND DIMENSIONS





- 1. Gate
- 2. Drain
- 3. Source





DISCLAIMER

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